

January 2008

74AC377, 74ACT377 Octal D-Type Flip-Flop with Clock Enable

Features

- I_{CC} reduced by 50%
- Ideal for addressable register applications
- Clock enable for address and data synchronization applications
- Eight edge-triggered D-type flip-flops
- Buffered common clock
- Outputs source/sink 24mA
- See 273 for master reset version
- See 373 for transparent latch version
- See 374 for 3-STATE version
- ACT377 has TTL-compatible inputs

General Description

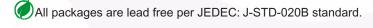
The AC/ACT377 has eight edge-triggered, D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) input loads all flip-flops simultaneously, when the Clock Enable (\overline{CE}) is LOW.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output. The $\overline{\text{CE}}$ input must be stable only one setup time prior to the LOW-to-HIGH clock transition for predictable operation.

Ordering Information

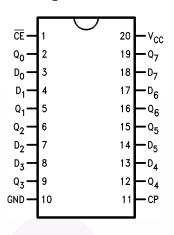
Order Number	Package Number	Package Description
74AC377SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74AC377SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC377MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT377SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ACT377SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT377MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT377PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



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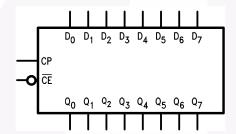
Connection Diagram



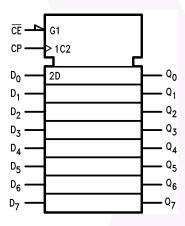
Pin Descriptions

Pin Names	Description				
D ₀ –D ₇	Data Inputs				
CE	Clock Enable (Active LOW)				
Q ₀ –Q ₇	Data Outputs				
СР	Clock Pulse Input				

Logic Symbols



IEEE/IEC



Mode Select-Function Table

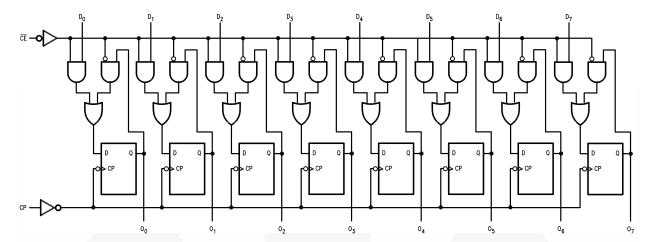
		Inputs	Outputs	
Operating Mode	СР	CE	D _n	Q _n
Load '1'	~	L	Н	Н
Load '0'	~	L	L	L
Hold (Do Nothing)	~	Н	X	No Change
	X	Н	Х	No Change

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current	
	$V_{I} = -0.5V$	–20mA
	$V_{I} = V_{CC} + 0.5V$	+20mA
V _I	DC Input Voltage	-0.5V to V _{CC} + 0.5V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	–20mA
	$V_O = V_{CC} + 0.5V$	+20mA
Vo	DC Output Voltage	-0.5V to V _{CC} + 0.5V
Io	DC Output Source or Sink Current	±50mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Output Pin	±50mA
T _{STG}	Storage Temperature	−65°C to +150°C
T_J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	
	AC	2.0V to 6.0V
	ACT	4.5V to 5.5V
VI	Input Voltage	0V to V _{CC}
V _O	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	-40°C to +85°C
ΔV / Δt	Minimum Input Edge Rate, AC Devices:	125mV/ns
	V_{IN} from 30% to 70% of V_{CC} , V_{CC} @ 3.3V, 4.5V, 5.5V	
ΔV / Δt	Minimum Input Edge Rate, ACT Devices:	125mV/ns
	$V_{\rm IN}$ from 0.8V to 2.0V, $V_{\rm CC}$ @ 4.5V, 5.5V	

DC Electrical Characteristics for AC

	V _{CC} T _A = +29		+25°C $T_A = -40$ °C to +85°C				
Symbol	Parameter	(V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH	3.0	V _{OUT} = 0.1V	1.5	2.1	2.1	V
	Level Input Voltage	4.5	or V _{CC} – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V _{IL}	Maximum LOW	3.0	$V_{OUT} = 0.1V$	1.5	0.9	0.9	V
	Level Input Voltage	4.5	or V _{CC} – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V _{OH}	Minimum HIGH	3.0	$I_{OUT} = -50\mu A$	2.99	2.9	2.9	V
	Level Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76	
V _{OL}	Maximum LOW	3.0	$I_{OUT} = 50\mu A$	0.002	0.1	0.1	V
	Level Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I _{IN} ⁽³⁾	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽²⁾		V _{OHD} = 3.85V Min.			- 75	mA
I _{CC} ⁽³⁾	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. Maximum test duration 2.0ms, one output loaded at a time.
- 3. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC} .

DC Electrical Characteristics for ACT

		V _{CC} T _A =		T _A = +	-25°C	T _A = -40°C to +85°C	
Symbol	Parameter	(V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Level Input Voltage	5.5	V _{CC} – 0.1V	1.5	2.0	2.0	
V _{IL}	Maximum LOW	4.5	$V_{OUT} = 0.1V$ or	1.5	0.8	0.8	V
	Level Input Voltage	5.5	V _{CC} – 0.1V	1.5	0.8	0.8	
V _{OH}	Minimum HIGH	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Level Output Voltage	5.5		5.49	5.4	5.4	
	voitage	4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V _{OL}	Maximum LOW	4.5	$I_{OUT} = 50\mu A$	0.001	0.1	0.1	V
	Level Output Voltage	5.5		0.001	0.1	0.1	
	voitage	4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I _{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	± 1.0	μΑ
I _{CCT}	Maximum I _{CC} /Input	5.5	$V_{I} = V_{CC} - 2.1V$	0.6		1.5	mA
I_{OLD}	Minimum Dynamic	5.5	$V_{OLD} = 1.65V Max.$			75	mA
I _{OHD}	Output Current ⁽⁵⁾		V _{OHD} = 3.85V Min.			- 75	mA
I _{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.

AC Electrical Characteristics for AC

			T _A = +25°C		$T_A = -40$ °C to +85°C			
Symbol	Parameter	V _{CC} (V) ⁽⁶⁾	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock	3.3	90	125		75		MHz
	Frequency	5.0	140	175		125		
t _{PLH}	Propagation Delay,	3.3	3.0	8.0	13.0	1.5	14.0	ns
	CP to Q _n	5.0	2.0	6.0	9.0	1.5	10.0	
t _{PHL}	Propagation Delay,	3.3	3.5	8.5	13.0	2.0	14.5	ns
	CP to Q _n	5.0	2.5	6.5	10.0	1.5	11.0	

Note:

6. Voltage range 3.3 is 3.3V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V

AC Operating Requirements for AC

				-25°C, 50pF	$T_A = -40$ °C to +85°C, $C_L = 50$ pF	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Тур.	Gua	ranteed Minimum	Units
t _S	Setup Time, HIGH or LOW,	3.3	3.5	5.5	6.0	ns
	D _n to CP	5.0	2.5	4.0	4.5	
t _H	Hold Time, HIGH or LOW,	3.3	-2.0	0	0	ns
	D _n to CP	5.0	-1.0	1.0	1.0	
t _S	Setup Time, HIGH or LOW,	3.3	4.0	6.0	7.5	ns
	CE to CP	5.0	2.5	4.0	4.5	
t _H	Hold Time, HIGH or LOW,	3.3	-3.5	0	0	ns
	CE to CP	5.0	-2.0	1.0	1.0	
t _W	CP Pulse Width,	3.3	3.5	5.5	6.0	ns
	HIGH or LOW	5.0	2.5	4.0	4.5	

Note

7. Voltage range 3.3 is 3.0V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V

AC Electrical Characteristics for ACT

			T _A = +25°C, C _L = 50pF		$T_A = -40$ °C to +85°C, $C_L = 50$ pF			
Symbol	Parameter	V _{CC} (V) ⁽⁸⁾	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock Frequency	5.0	140	175		125		MHz
t _{PLH}	Propagation Delay, CP to Q _n	5.0	3.0	6.5	9.0	2.5	10.0	ns
t _{PHL}	Propagation Delay, CP to Q _n	5.0	3.5	7.0	10.0	2.5	11.0	ns

Note:

8. Voltage Range 5.0 is $5.0V \pm 0.5V$

AC Operating Requirements for ACT

			T _A = +25°C, C _L = 50pF		$T_A = -40$ °C to +85°C, $C_L = 50$ pF	
Symbol	Parameter	$V_{CC}(V)^{(9)}$	Тур.	Gu	aranteed Minimum	Units
t _S	Setup Time, HIGH or LOW, D_n to CP	5.0	2.5	4.5	5.5	ns
t _H	Hold Time, HIGH or LOW, D _n to CP	5.0	-1.0	1.0	1.0	ns
t _S	Setup Time, HIGH or LOW, CE to CP	5.0	2.5	4.5	5.5	ns
t _H	Hold Time, HIGH or LOW, CE to CP	5.0	-1.0	1.0	1.0	ns
t _W	CP Pulse Width, HIGH or LOW	5.0	2.0	4.0	4.5	ns

Note:

9. Voltage Range 5.0 is $5.0V \pm 0.5V$

Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C _{IN}	Input Capacitance	V _{CC} = OPEN	4.5	pF
C _{PD}	Power Dissipation Capacitance	V _{CC} = 5.0V	90.0	pF

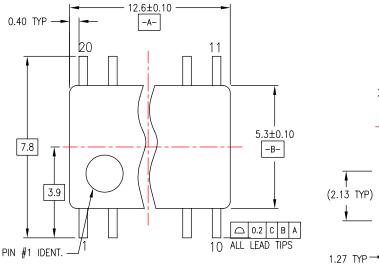
Physical Dimensions 13.00 12.60 11.43 В 9.50 10.65 7.60 10.00 7.40 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 0.20 0.10 C 0.30 0.10 0.75 0.25 × 45° SEATING PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L (1.40)DETAIL A F) DRAWING FILENAME: MKT-M20BREV3

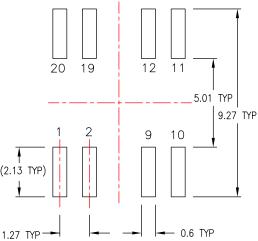
Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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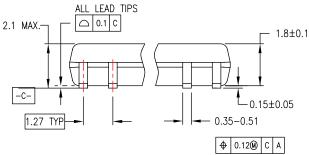
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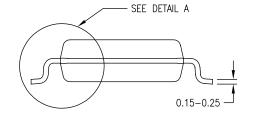
Physical Dimensions (Continued)









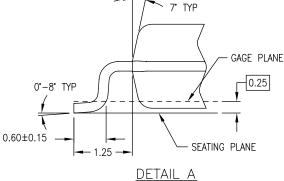


DIMENSIONS ARE IN MILLIMETERS

NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M20DREVC

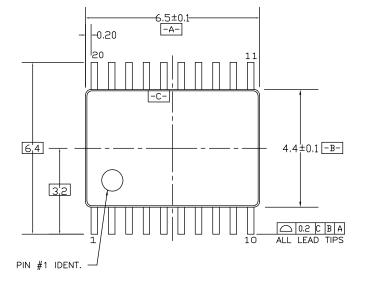
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

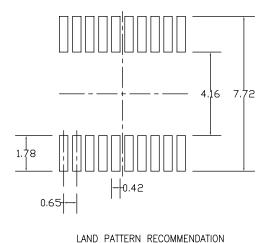
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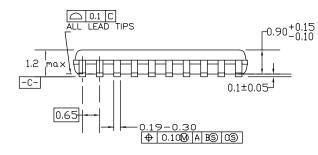
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Physical Dimensions (Continued)



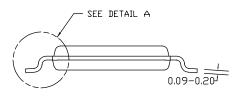


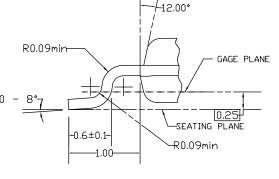


DIMENSIONS ARE IN MILLIMETERS

NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.





DETAIL A

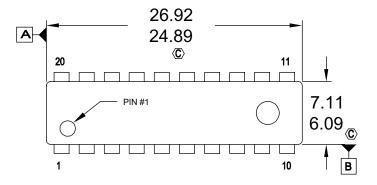
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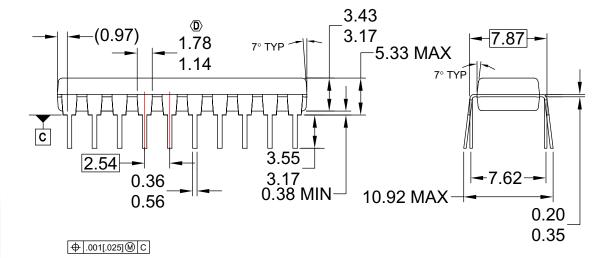
Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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Physical Dimensions (Continued)





NOTES:
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VARIATIONS AD.

B. ALL DIMENSIONS ARE IN MILLIMETERS

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0.25MM.
(D) DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED

E. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

F. DRAWING FILE NAME: N20AREV8

Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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